

Title (en)

METHOD OF METAL PLATING OF POLYMER-CONTAINING SUBSTRATES

Title (de)

VERFAHREN ZUR METALLBESCHICHTUNG VON POLYMERHALTIGEN SUBSTRATEN

Title (fr)

PROCÉDÉ DE PLACAGE MÉTALLIQUE DE SUBSTRATS CONTENANT UN POLYMÈRE

Publication

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Application

EP 19716434 A 20190412

Priority

- EP 18168933 A 20180424
- EP 2019059459 W 20190412

Abstract (en)

[origin: WO2019206682A1] Method of forming a metallic plating (9) on a substrate (1), comprising the steps of: - providing a substrate (1) comprising a hydrocarbon-based polymer containing C-C and either or both of C-H and N-H bonds; - covalently bonding an azide-containing primer compound (3) to said substrate (1) by C-H and/or N-H insertion, said primer compound (3) comprising molecules each having at plurality of C-H and/or C-N insertion sites; - in the absence of in-situ polymerisation, covalently bonding a pre-synthesised chelating polymer (5) to said primer compound (3) by C-H and/or N-H insertion, said chelating polymer (5) being capable of forming ligand bonds with metal atoms or ions; - dispersing a plating catalyst (7) in said pre-synthesised polymer (5); - forming said metallic plating (9) on said pre-synthesised polymer (5) by means of electroless plating or electroplating.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

See references of WO 2019206682A1

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